Product Information Sheet

EPO-TEK® HYB-353ND-TX3 PMF Syringe

Date: August 2024	**Rev:** VII
Material Description:	A single component, high temperature hybrid epoxy for semiconductor and fiber optic applications. It is designed to have similar cured performance to EPO-TEK® 353ND; modified to allow for initial UV tacking. It is a higher thixotropy version of EPO-TEK® HYB-353ND.
Number of Components:	Single
Mix Ratio by Weight:	N/A
Recommended Cure:	**Initial Tack 100mW/cm^2 for 10 seconds @ 240-365 nm + 150°C/30 Minutes Thermal Cure**
Minimum Alternative Cure:	Initial Tack 100mW/cm^2 for 10 seconds @ 240-365 nm + 100°C/30 Minutes Thermal Cure Initial Tack 100mW/cm^2 for 10 seconds @ 240-365 nm + 80°C/1 Hour Thermal Cure
Specific Gravity:	1.18
Pot Life:	< 3 Days
Shelf Life:	Six months at -40°C

NOTES:

- To prevent gelation, keep containers away from light sources.
- Performance properties (rheology, conductivity, others) of the Products may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

MATERIAL CHARACTERISTICS: Cure condition: Initial Tack 100mW/cm^2 for 10 seconds @ 240-365 nm + 150°C/30 Minutes

To be used as a guide only, not as a specification. Different batches, conditions and applications yield differing results.

* denotes test on lot acceptance basis Data below is not guaranteed.

PHYSICAL PROPERTIES:			
* **Color (before cure):**		Clear/Slightly Yellow	
* **Consistency:**		Pourable paste	
* **Viscosity (23°C) @ 10 rpm:**		25,000-41,000	cPs
Thixotropic Index:		1.3	
* **Glass Transition Temp:**		≥ 80	°C (Dynamic Cure:20-200°C/ISO 25 Min + Ramp -10-200°C @ 20°C/Min)
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	71	x 10^{-6} in/in°C
	Above Tg:	178	x 10^{-6} in/in°C
Shore D Hardness:		85	
Die Shear @ 23°C:		≥ 15	Kg 5,334 psi
Degradation Temp:		399	°C
Weight Loss:	**@ 200°C**	0.19	**%**
	@ 250°C	0.71	**%**
	@ 300°C	1.81	**%**
Suggested Operating Temperature:		< 350	°C (Intermittent)
Storage Modulus:		520,395	psi
* **Particle Size:**		≤ 20	microns

OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	≥ 50% @ 550	nm
	≥ 95% @ 1,100-1,600	nm
	≥ 98% @ 800-1,000	nm
Refractive Index:	1.5456 @ 589	nm

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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